

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: Miwa KOZAWA et al. Group Art Unit: 1752

Serial No.: 10/629,806 Examiner: LEE, SIN J

Filed: July 30, 2003 Confirmation No.: 9494

For: RESIST PATTERN THICKENING MATERIAL, PROCESS FOR

FORMING RESIST PATTERN, AND PROCESS FOR MANUFACTURING

SEMICONDUCTOR DEVICE

Attorney Docket No.: 030923 Customer Number: 38834

## RESPONSE UNDER 37 CFR §1.111

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

February 8, 2005

Sir:

This paper is in response to the Office Action dated November 29, 2004.

Remarks begin on page 2 of this paper.